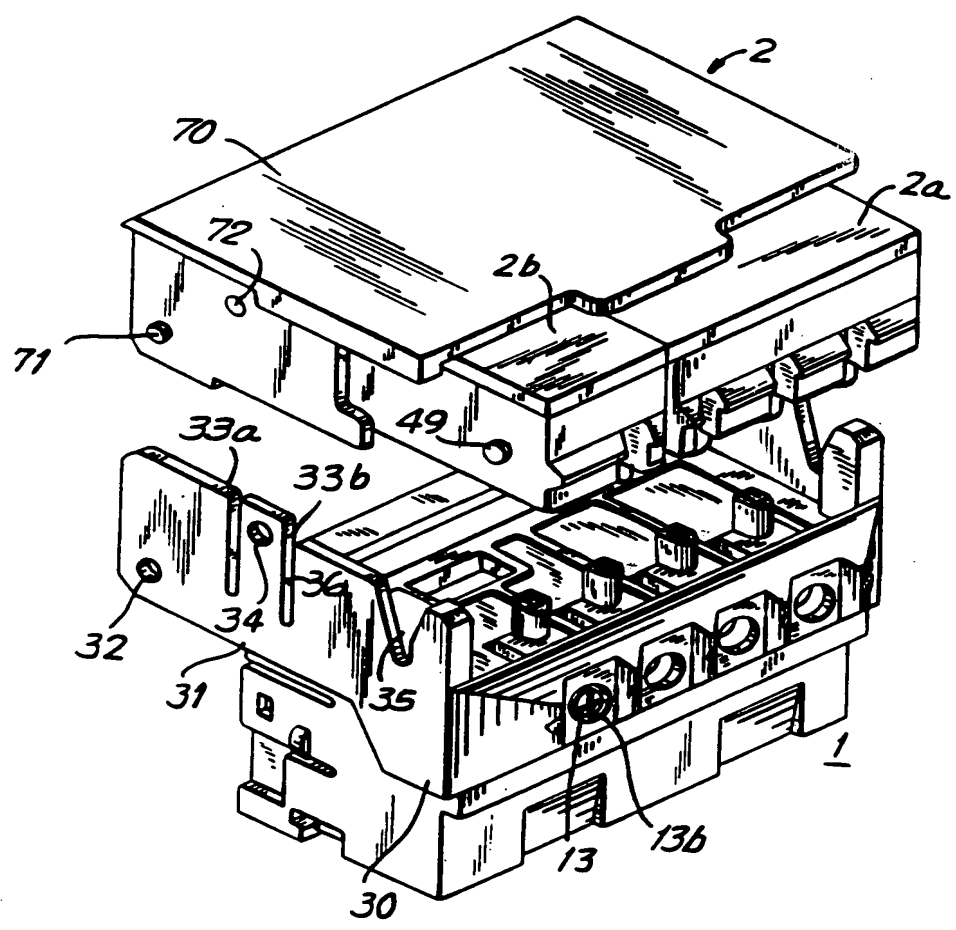


5158377

07 620411
330
61

FIG. 1



A detailed cross-sectional diagram of a multi-layered electronic device assembly. The top layer is labeled 60. Below it is a thick substrate or core labeled 2. A central horizontal component is labeled 20, with internal features 11 and 12c. To the right, there's a vertical stack of components including 12b and B. Below the main body, there are several other layers and components labeled 19, 14, 13a, 13, 12, 16, 21, 15, 17, and 18. At the bottom right, a box labeled 25 contains the text "PRINT CONTROL".

FIG. 3

07 620411

FIG. 4

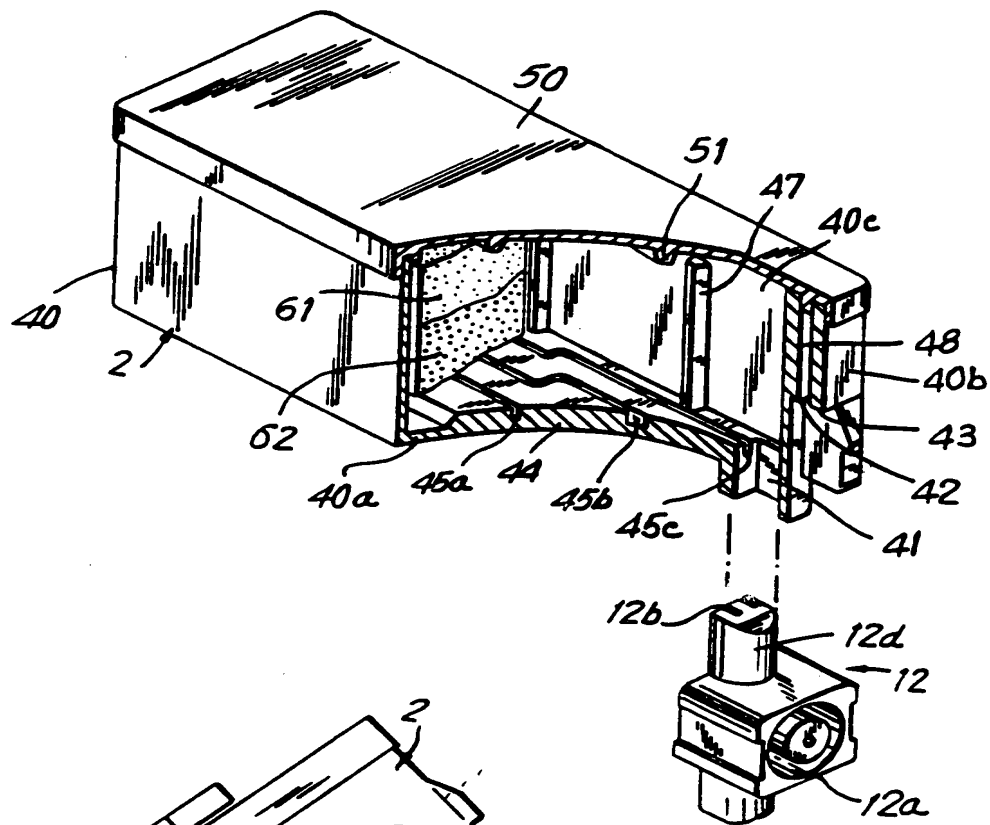


FIG. 5

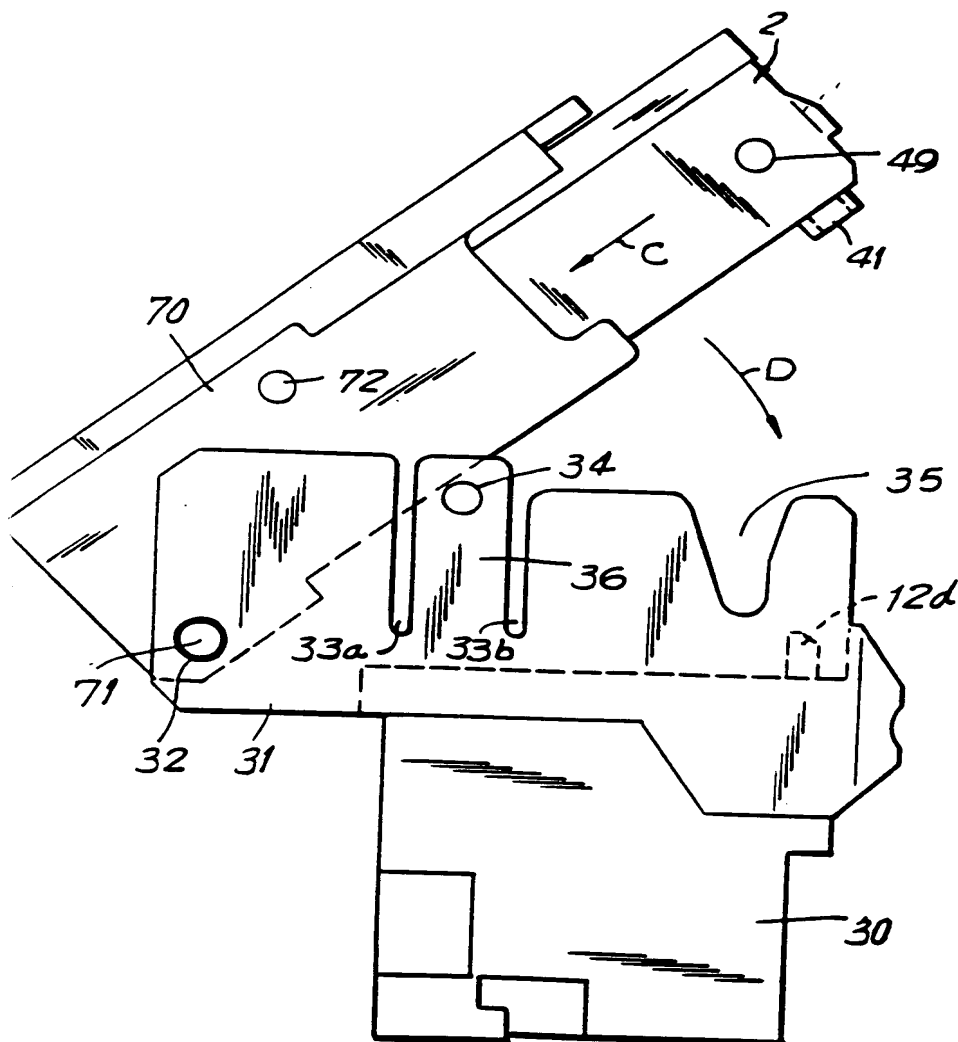


FIG. 6

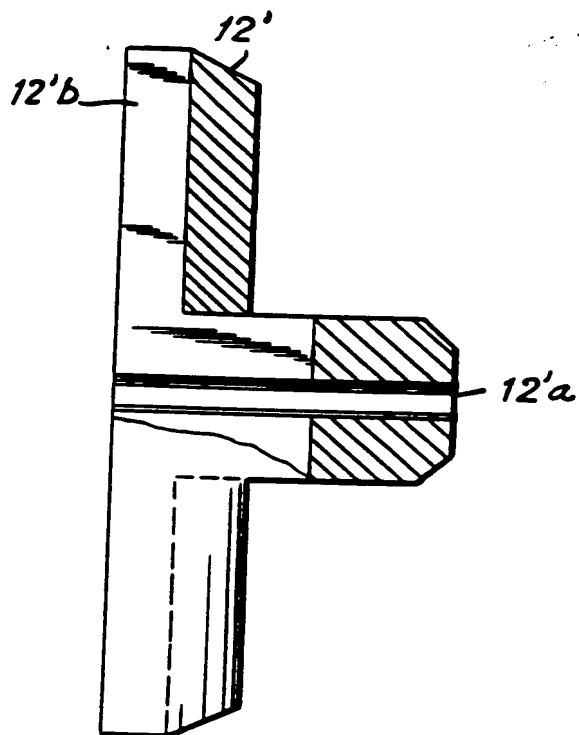


FIG. 7

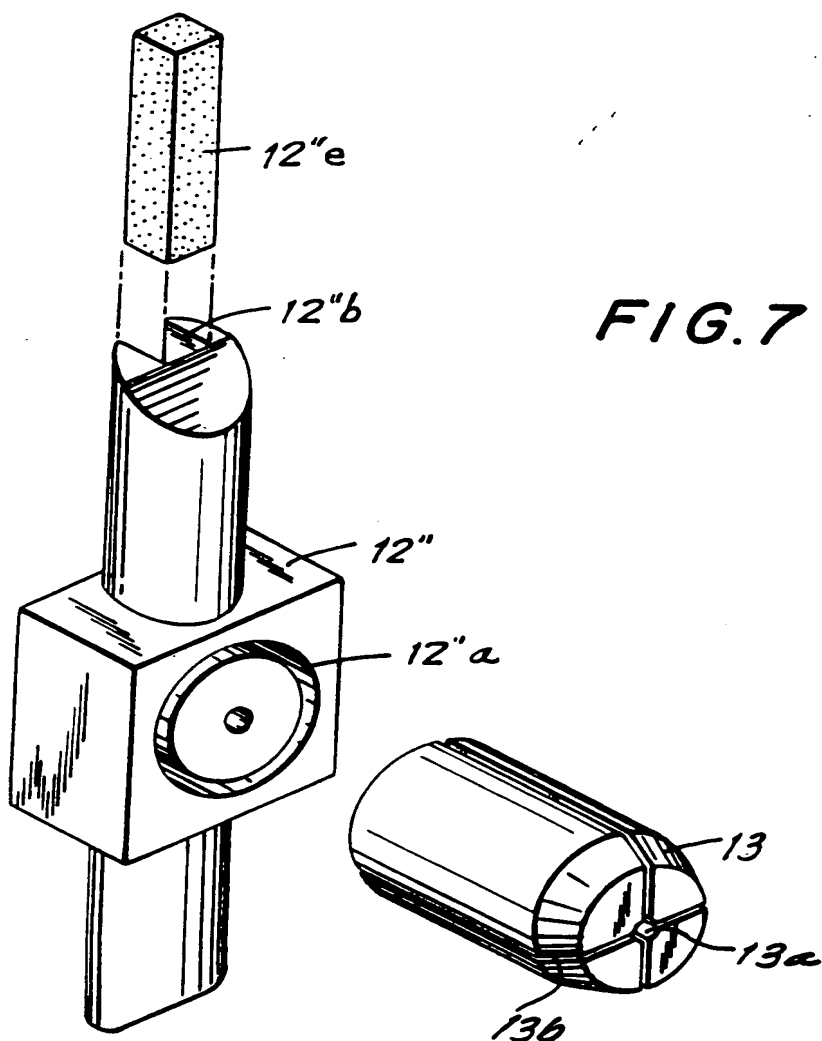


FIG. 8

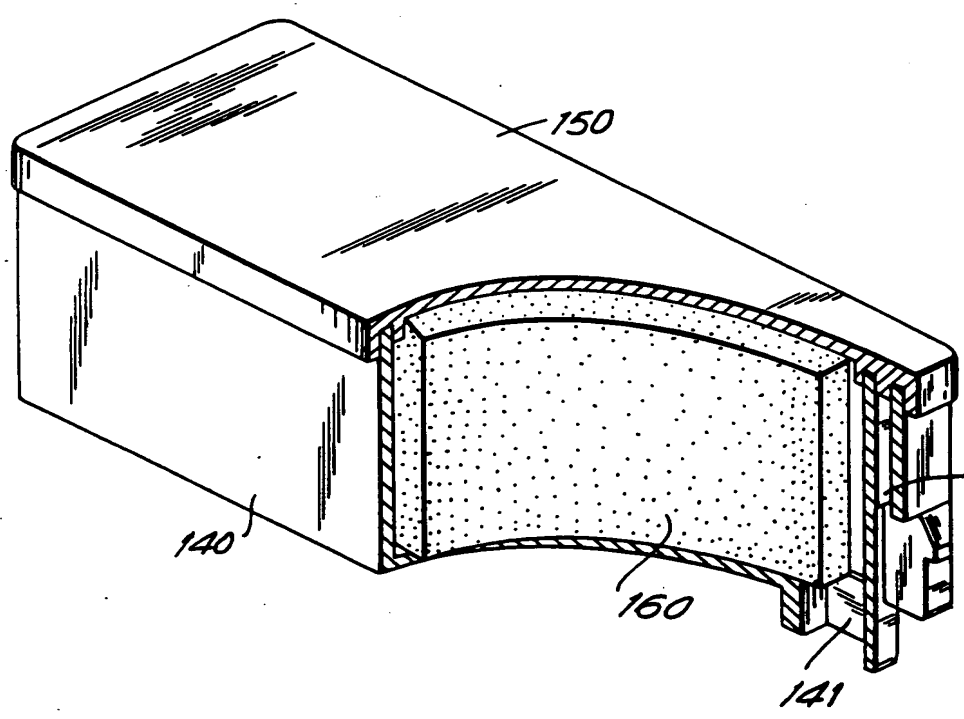
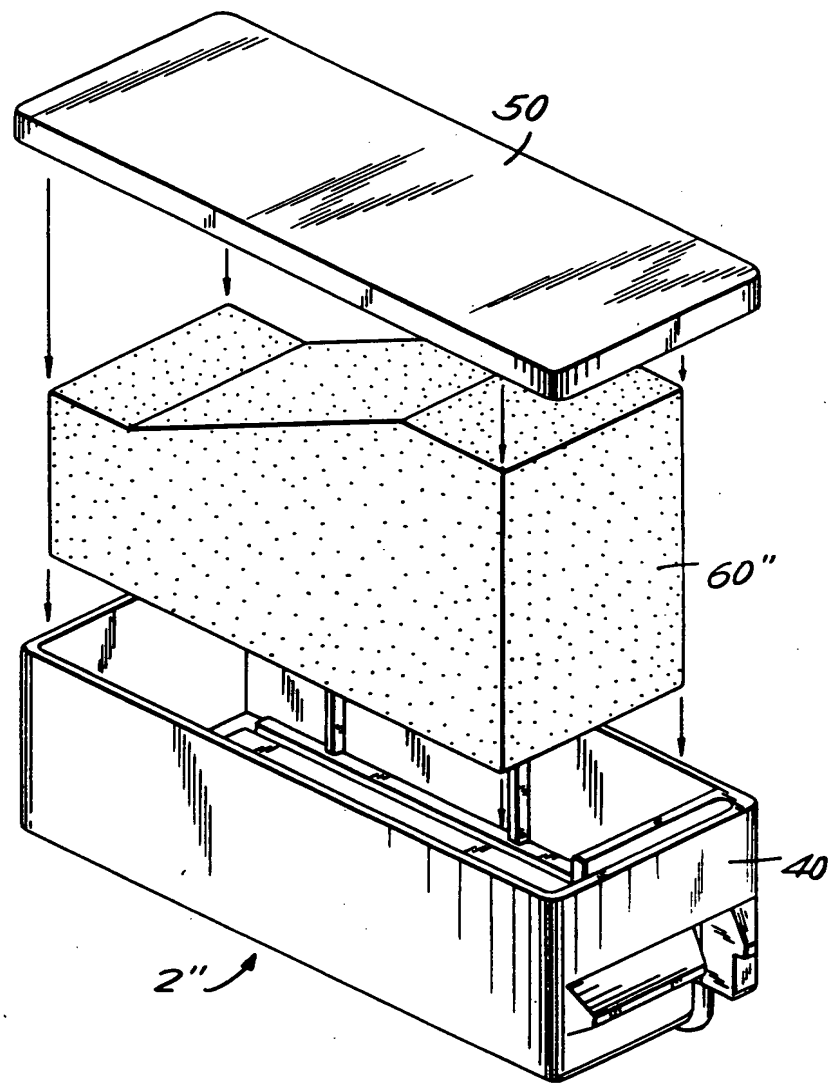


FIG. 9

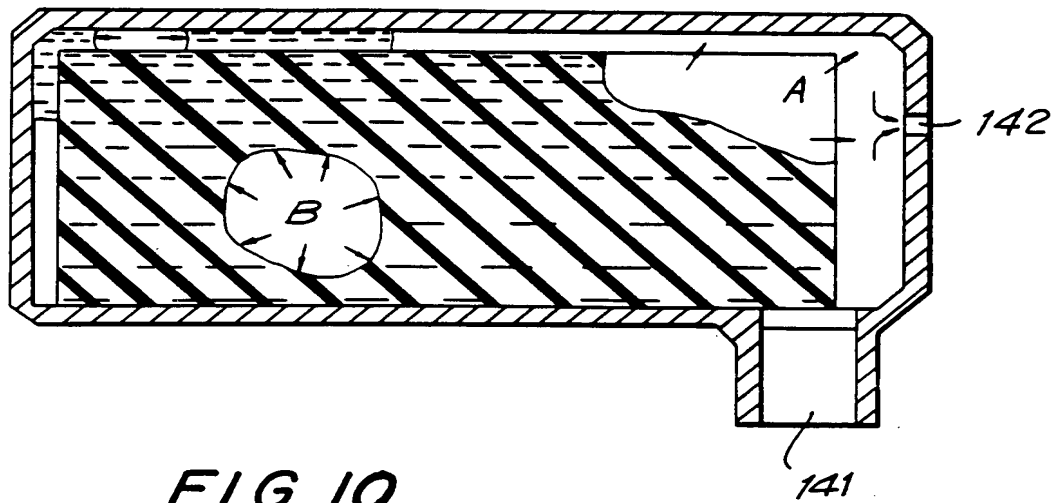


FIG. 10

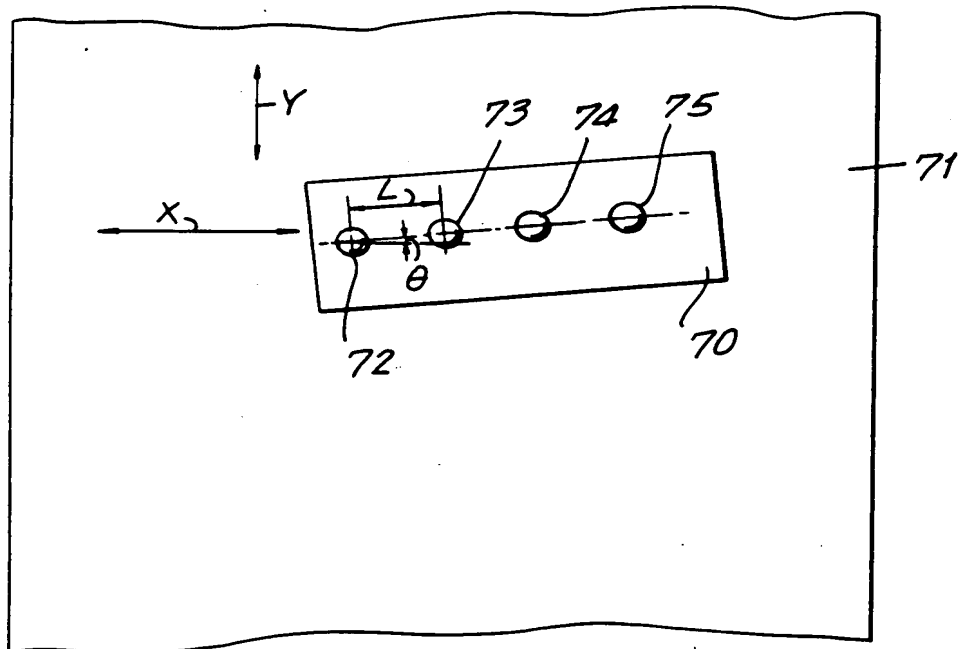


FIG. 11